ABSTRACT OF THE DISCLOSURE

A method for manufacturing micro electro-mechanical systems includes forming an insulation layer on an upper surface of a semiconductor substrate, forming a structure layer on an upper surface of the insulation layer and etching the structure layer, forming an under bump metal on a predetermined position of an upper surface of the structure layer, forming a via hole in a glass substrate corresponding to the position of the under bump metal and in a shape such that the via hole is larger in diameter at an upper surface of the glass substrate than at a lower surface of the glass substrate, wherein the glass substrate is bonded to the upper surface of the structure layer and creates a vacuum chamber that protects a structure of the structure layer, and arranging a solder ball in the via hole and bonding the solder ball to the under bump metal.